## Purpose
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps N/A</td>
<td>2</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | N/A | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hexagonal Screwdriver (T15)</td>
<td>T15 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Philips Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Knife</td>
<td></td>
</tr>
<tr>
<td>Side Cutter</td>
<td></td>
</tr>
<tr>
<td>Star key wrench</td>
<td></td>
</tr>
<tr>
<td>Slotted Screwdriver</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassembly process – Base
2. Disassembly process – Main Device
3. Disassembly process – Panel
4. Disassembly process – Adaptor
5. 
6. 
7. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Description of the sample submitted for assessment
8. Description of the disassembly sequences.

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PSG instructions for this template are available at EL-MF877-01
Separate the panel by loosening 4 screws.

Separate the metal sicket by loosening 8 screws.

Separate the rubber feet by loosening 4 screws.

Take off the adaptor.

Separate the metal lock of adaptor by loosening 1 screw.

Open the side panels of base.

Separate the metal sicket by loosening 14 screws.

Tear off the sticker.

Open the housing of base.

**Disassembly process (Base) Contd.**
Separate the housing of base by loosening 4 screws.

Open the housing of hinge.

Separate the housing of hinge by loosening 1 screw.

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**Disassembly process (Main Device)**

Open the side covers of panel.

Take off the cover of connector.

Separate the metal frame form cover.

Separate the plastic housing of metal frame by loosening 5 screws.

Tear off the stickers and pads.

Separate the metal housing of panel by loosening 4 screws.

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**Disassembly process (Main Device) Contd.**
Separate the plastic frame of USB by loosening 15 screws.

Separate the speakers by loosening 4 screws.

Separate the PCB assembly and HD socket by loosening 10 screws.

Separate the Hard Disk by loosening 6 screws.

Take off the battery.

Take off the RAM.

Separate the PCB assembly by loosening 2 screws.

Separate the metal frame of panel by loosening 10 screws.

Separate the panel.

**Disassembly process (Panel)**
Separate the cable.

Tear off tape.

Separate the touch panel.

Separate the optical films.

Separate the metal frame.

Separate the metal support by loosening 6 screws.

Take off PCB assembly.

Tear off the plastic film.

Take off LED of PCB assembly.
1. Tear off the pads and stickers.
2. Open the case.
3. Tear off the tape.
4. Separate the metal sheets by loosening 6 screws.
5. Separate the black plastic sheet.
6. Separate the metal frame by loosening 1 screw.
7. Cut off the cable.
8. Completed disassembly.

PSG instructions for this template are available at EL-MF877-01